

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| Meng-Jen Wang | 04/21/2011 |
| RECEIVING PARTY DATA | |
| Name: | Advanced Semiconductor Engineering, Inc. |
| Street Address: | No. 26, Chin 3rd Road |
| City: | Nantze Export Processing Zone, Kaohsiung |
| State/Country: | TAIWAN |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 13092866 |
| CORRESPONDENCE DATA | |
| <p>Fax Number: (480)345-4100</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 480-899-3021</p> <p>Email: info@patentaz.com</p> <p>Correspondent Name: George D. Morgan</p> <p>Address Line 1: 4635 S Lakeshore Dr.</p> <p>Address Line 4: Tempe, ARIZONA 85282</p> | |
| NAME OF SUBMITTER: | George D. Morgan |
| <p>Total Attachments: 1</p> <p>source=ASE2368Assignment#page1.tif</p> | |

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PATENT
REEL: 026177 FRAME: 0718

ASSIGNMENT OF APPLICATION

WHEREAS, I, **Meng-Jen Wang**, of No.68, Heping Rd., Pingtung City, Pingtung County 900, Taiwan, R.O.C. and a citizen of Taiwan R.O.C. ("Assignor"), have an interest in the invention entitled **"SEMICONDUCTOR ELEMENT HAVING CONDUCTIVE VIAS AND SEMICONDUCTOR PACKAGE HAVING A SEMICONDUCTOR ELEMENT WITH CONDUCTIVE VIAS AND METHOD FOR MAKING THE SAME"** which is the subject of a United States application for patent entitled above and in a Taiwan patent application filed on October 11, 2010, with serial number 099134620; and

WHEREAS, **Advanced Semiconductor Engineering, Inc.**, a corporation organized and existing under and by virtue of the laws of Taiwan R.O.C. with an address at No. 26, Chin 3rd Road, Nantze Export Processing Zone, Kaohsiung, Taiwan R.O.C. ("Assignee"), is desirous of acquiring Assignor's interest in the invention;

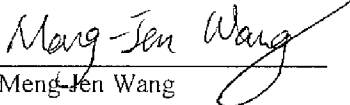
NOW THEREFORE, Assignor acknowledges receipt and adequacy of good and valuable consideration in exchange for this Assignment, and assigns to Assignee and its successors in interest, the full and exclusive right, title and interest to the invention described in the patent application listed above, in the United States of America and all foreign countries, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, for the full term of the patent, including extensions of time, the same as if held by Assignor had this Assignment not been made.

Assignor covenants and agrees to cooperate with Assignee and execute all instruments or documents requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to the following: non-provisional utility, provisional, continuation, continuation-in-part, divisional, renewal or substitute, reissue, re-examination, or extension.

Assignor covenants and agrees to cooperate with Assignee in any litigation regarding the invention, patents or applications regarding the invention, including testifying for the benefit of Assignee.

Assignor covenants that no assignment, sale or agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

Signed and Accepted by:


Meng-Jen Wang

2011.04.21
Date